MC14528B

Dual Monostable Multivibrator

The MC14528B is a dual, retriggerable, resettable monostable multivibrator. It may be triggered from either edge of an input pulse, and produces an output pulse over a wide range of widths, the duration of which is determined by the external timing components, C_X and R_X.

Features

- Separate Reset Available
- Diode Protection on All Inputs
- Triggerable from Leading or Trailing Edge Pulse
- Supply Voltage Range = 3.0 Vdc to 18 Vdc
- Capable of Driving Two Low−power TTL Loads or One Low−power Schottky TTL Load Over the Rated Temperature Range
- This part should only be used in new designs where the pulse width is < 10 μs
  Note: For designs requiring a pulse width > 10 μs, please see MC14538, which is pin−for−pin compatible
- These Devices are Pb−Free and are RoHS Compliant

MAXIMUM RATINGS (Voltages Referenced to V_{SS})

Rating	Symbol	Value	Unit
DC Supply Voltage Range	V_{DD}	−0.5 to +18.0	V
Input or Output Voltage Range (DC or Transient)	V_{in}, V_{out}	−0.5 to V_{DD} + 0.5	V
Input or Output Current (DC or Transient) per Pin	I_{in}, I_{out}	±10	mA
Power Dissipation, per Package (Note 1)	P_D	500	mW
Ambient Temperature Range	T_A	−55 to +125	°C
Storage Temperature Range	T_{stg}	−65 to +150	°C
Lead Temperature (8−Second Soldering)	T_L	260	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Temperature Derating:
   Plastic “P and D/DW” Packages: − 7.0 mW/°C From 65°C To 125°C

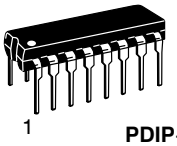
This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high−impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range $V_{SS} \le (V_{in}$ or $V_{out}) \le V_{DD}$.

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either V_{SS} or V_{DD}). Unused outputs must be left open.

ON Semiconductor®

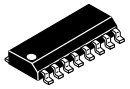
http://onsemi.com

MARKING DIAGRAMS



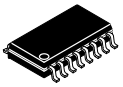
PDIP−16
P SUFFIX
CASE 648



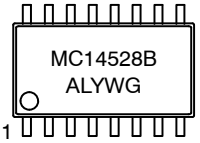


SOIC−16
D SUFFIX
CASE 751B





SOEIAJ−16
F SUFFIX
CASE 966



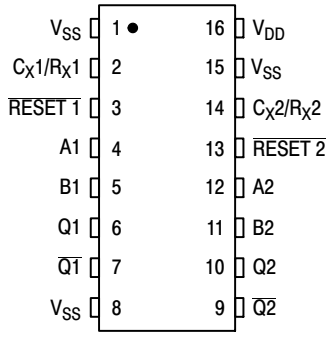
A = Assembly Location
WL = Wafer Lot
YY, Y = Year
WW, W = Work Week
G = Pb−Free Package

ORDERING INFORMATION

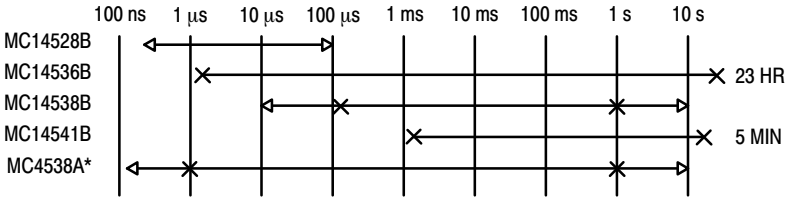
See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

© Semiconductor Components Industries, LLC, 2011

PIN ASSIGNMENT



ONE−SHOT SELECTION GUIDE

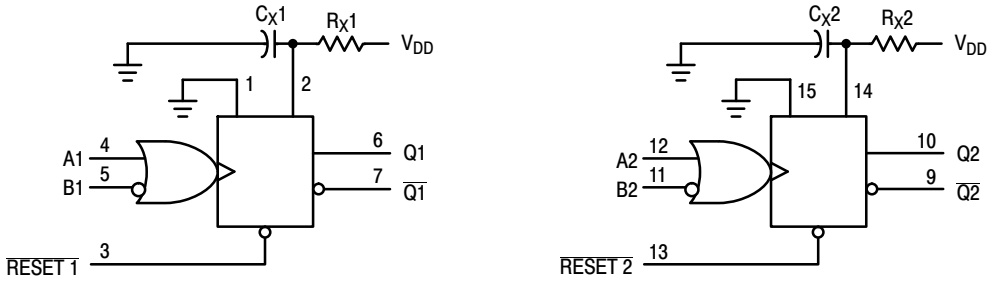


*LIMITED OPERATING VOLTAGE (2−6 V)

TOTAL OUTPUT PULSE WIDTH RANGE ⟷

RECOMMENDED PULSE WIDTH RANGE ×——×

BLOCK DIAGRAM



V_{DD} = PIN 16
V_{SS} = PIN 1, PIN 8, PIN 15
R_X AND C_X ARE EXTERNAL COMPONENTS

FUNCTION TABLE

Inputs			Outputs	
Reset	**A**	**B**	**Q**	**$\overline{Q}$**
H	↗	H	⊓	⊔
H	L	↘	⊓	⊔
H	↗↘	L	Not Triggered	
H	H	↗↘	Not Triggered	
H	L, H, ↘	H	Not Triggered	
H	L	L, H, ↗	Not Triggered	
L	X	X	L	H
↘↗	X	X	Not Triggered	

ELECTRICAL CHARACTERISTICS (Voltages Referenced to V_{SS})

Characteristic	Symbol	V_{DD} Vdc	– 55°C Min	– 55°C Max	25°C Min	25°C Typ (Note 2)	25°C Max	125°C Min	125°C Max	Unit
Output Voltage "0" Level V_{in} = V_{DD} or 0	V_{OL}	5.0 10 15	– – –	0.05 0.05 0.05	– – –	0 0 0	0.05 0.05 0.05	– – –	0.05 0.05 0.05	Vdc
"1" Level V_{in} = 0 or V_{DD}	V_{OH}	5.0 10 15	4.95 9.95 14.95	– – –	4.95 9.95 14.95	5.0 10 15	– – –	4.95 9.95 14.95	– – –	Vdc
Input Voltage "0" Level (V_O = 4.5 or 0.5 Vdc) (V_O = 9.0 or 1.0 Vdc) (V_O = 13.5 or 1.5 Vdc)	V_{IL}	5.0 10 15	– – –	1.5 3.0 4.0	– – –	2.25 4.50 6.75	1.5 3.0 4.0	– – –	1.5 3.0 4.0	Vdc
"1" Level (V_O = 0.5 or 4.5 Vdc) (V_O = 1.0 or 9.0 Vdc) (V_O = 1.5 or 13.5 Vdc)	V_{IH}	5.0 10 15	3.5 7.0 11	– – –	3.5 7.0 11	2.75 5.50 8.25	– – –	3.5 7.0 11	– – –	Vdc
Output Drive Current (V_{OH} = 2.5 Vdc) Source (V_{OH} = 4.6 Vdc) (V_{OH} = 9.5 Vdc) (V_{OH} = 13.5 Vdc)	I_{OH}	5.0 5.0 10 15	–1.2 –0.64 –1.6 –4.2	– – – –	–1.0 –0.51 –1.3 –3.4	–1.7 –0.88 –2.25 –8.8	– – – –	–0.7 –0.36 –0.9 –2.4	– – – –	mAdc
(V_{OL} = 0.4 Vdc) Sink (V_{OL} = 0.5 Vdc) (V_{OL} = 1.5 Vdc)	I_{OL}	5.0 10 15	0.64 1.6 4.2	– – –	0.51 1.3 3.4	0.88 2.25 8.8	– – –	0.36 0.9 2.4	– – –	mAdc
Input Current	I_{in}	15	–	±0.1	–	±0.00001	±0.1	–	±1.0	μAdc
Input Capacitance (V_{in} = 0)	C_{in}	–	–	–	–	5.0	7.5	–	–	pF
Quiescent Current (Per Package)	I_{DD}	5.0 10 15	– – –	5.0 10 20	– – –	0.005 0.010 0.015	5.0 10 20	– – –	150 300 600	μAdc
Total Supply Current at an external load Capacitance (C_L) and at external timing capacitance (C_X), use the formula. (Note 3)	I_T	–	$I_T(C_L, C_X) = [(C_L + 0.36C_X)V_{DD}f + 2x10^{-8} R_XC_X(V_{DD}^{-2})^2f] \times 10^{-3}$ where: I_T in μA (per circuit), C_L and C_X in pF, R_X in megohms, V_{DD} in Vdc, f in kHz is input frequency.							μAdc

2. Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.
3. The formulas given are for the typical characteristics only at 25°C.

SWITCHING CHARACTERISTICS (C_L = 50 pF, T_A = 25°C) (Note 4)

Characteristic	Symbol	C_X pF	R_X kΩ	V_{DD} Vdc	Min	Typ (Note 5)	Max	Unit
Output Rise and Fall Time t_{TLH}, t_{THL} = (1.5 ns/pF) C_L + 25 ns t_{TLH}, t_{THL} = (0.75 ns/pF) C_L + 12.5 ns t_{TLH}, t_{THL} = (0.55 ns/pF) C_L + 9.5 ns	t_{TLH}, t_{THL}	–	–	 5.0 10 15	 – – –	 100 50 40	 200 100 80	ns
Turn−Off, Turn−On Delay Time — A or B to Q or $\overline{Q}$ t_{PLH}, t_{PHL} = (1.7 ns/pF) C_L + 240 ns t_{PLH}, t_{PHL} = (0.66 ns/pF) C_L + 87 ns t_{PLH}, t_{PHL} = (0.5 ns/pF) C_L + 65 ns	t_{PLH}, t_{PHL}	15	5.0	 5.0 10 15	 – – –	 325 120 90	 650 240 180	ns
Turn−Off, Turn−On Delay Time — A or B to Q or $\overline{Q}$ t_{PLH}, t_{PHL} = (1.7 ns/pF) C_L + 620 ns t_{PLH}, t_{PHL} = (0.66 ns/pF) C_L + 257 ns t_{PLH}, t_{PHL} = (0.5 ns/pF) C_L + 185 ns	t_{PLH}, t_{PHL}	1000	10	 5.0 10 15	 – – –	 705 290 210	 – – –	ns
Input Pulse Width — A or B	t_{WH}	15	5.0	5.0 10 15	150 75 55	70 30 30	– – –	ns
	t_{WL}	1000	10	5.0 10 15	– – –	70 30 30	– – –	ns
Output Pulse Width — Q or $\overline{Q}$ (For C_X < 0.01 μF use graph for appropriate V_{DD} level.)	t_W	15	5.0	5.0 10 15	– – –	550 350 300	– – –	ns
Output Pulse Width — Q or $\overline{Q}$ (For C_X > 0.01 μF use formula: t_W = 0.2 R_X C_X Ln [V_{DD} − V_{SS}]) (Note 6)	t_W	10,000	10	5.0 10 15	15 10 15	30 50 55	45 90 95	μs
Pulse Width Match between Circuits in the same package	t1 − t2	10,000	10	5.0 10 15	– – –	6.0 8.0 8.0	25 35 35	%
Reset Propagation Delay — $\overline{Reset}$ to Q or $\overline{Q}$	t_{PLH}, t_{PHL}	15	5.0	5.0 10 15	– – –	325 90 60	600 225 170	ns
		1000	10	5.0 10 15	– – –	1000 300 250	– – –	ns
Retrigger Time	t_{rr}	15	5.0	5.0 10 15	0 0 0	– – –	– – –	ns
		1000	10	5.0 10 15	0 0 0	– – –	– – –	ns
External Timing Resistance	R_X	–	–	–	5.0	–	1000	kΩ
External Timing Capacitance	C_X	–	–	–	No Limits (Note 7)			μF

4. The formulas given are for the typical characteristics only at 25°C.
5. Data labelled “Typ” is not to be used for design purposes but is intended as an indication of the IC’s potential performance.
6. If C_X > 15 μF, Use Discharge Protection Diode D_X, per Figure 9.
7. $R_X$is in Ω, C_X is in farads, V_{DD} and V_{SS} in volts, PW_{out} in seconds.

ORDERING INFORMATION

Device	Package	Shipping†
MC14528BCPG	PDIP−16 (Pb−Free)	500 Units / Rail
MC14528BDG	SOIC−16 (Pb−Free)	48 Units / Rail
MC14528BDR2G	SOIC−16 (Pb−Free)	2500 / Tape & Reel
MC14528BFG	SOEIAJ−16 (Pb−Free)	50 Units / Rail
MC14528BFELG	SOEIAJ−16 (Pb−Free)	2000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

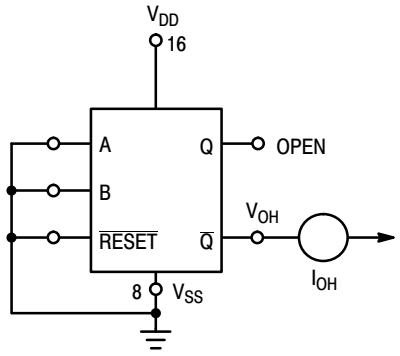


Figure 1. Output Source Current Test Circuit

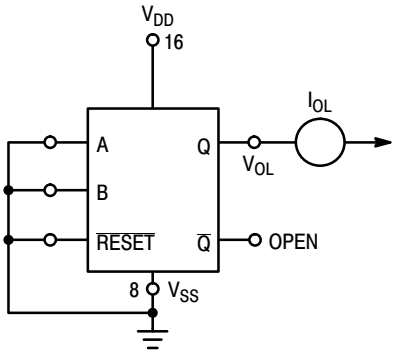
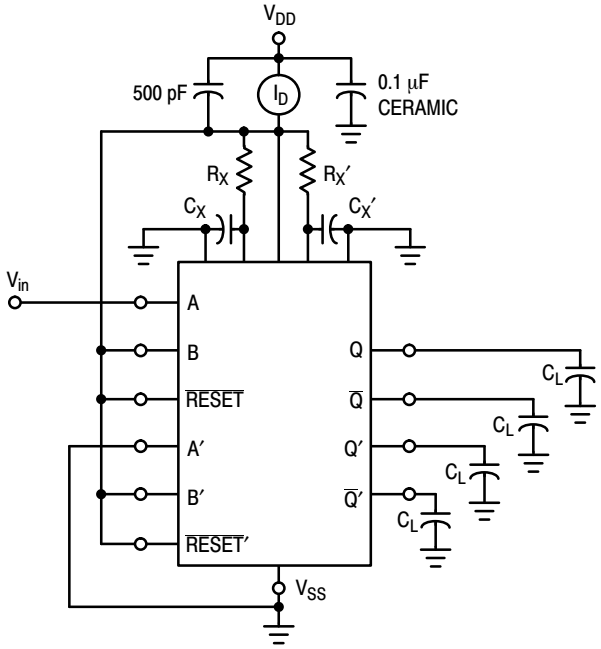


Figure 2. Output Sink Current Test Circuit



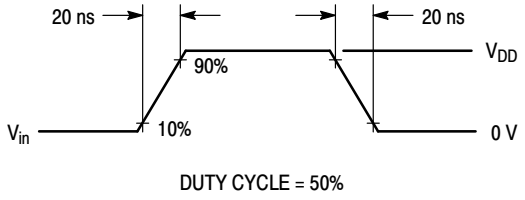
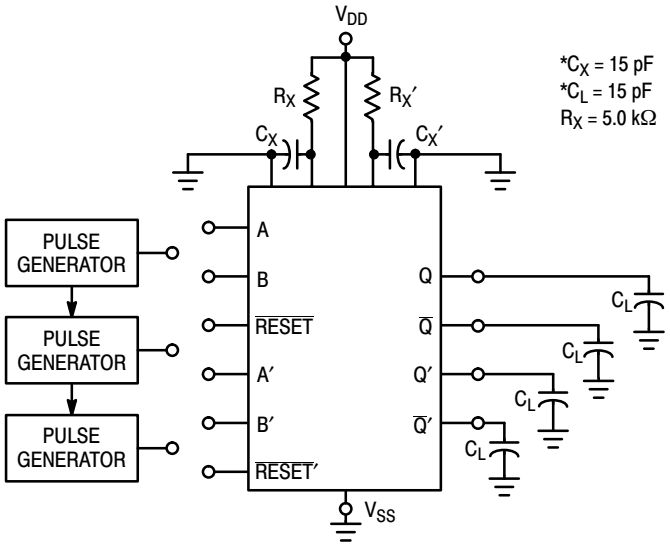


Figure 3. Power Dissipation Test Circuit and Waveforms



INPUT CONNECTIONS

Characteristics	$\overline{\text{Reset}}$	A	B
t_{PLH}, t_{PHL}, t_{TLH}, t_{THL}, t_W	V_{DD}	PG1	V_{DD}
t_{PLH}, t_{PHL}, t_{TLH}, t_{THL}, t_W	V_{DD}	V_{SS}	PG2
$t_{PLH(R)}$, $t_{PHL(R)}$, t_W	PG3	PG1	PG2

*Includes capacitance of probes, wiring, and fixture parasitic.

NOTE: AC test waveforms for PG1, PG2, and PG3 on next page.

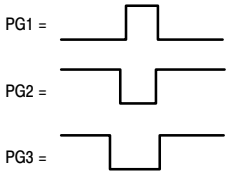


Figure 4. AC Test Circuit

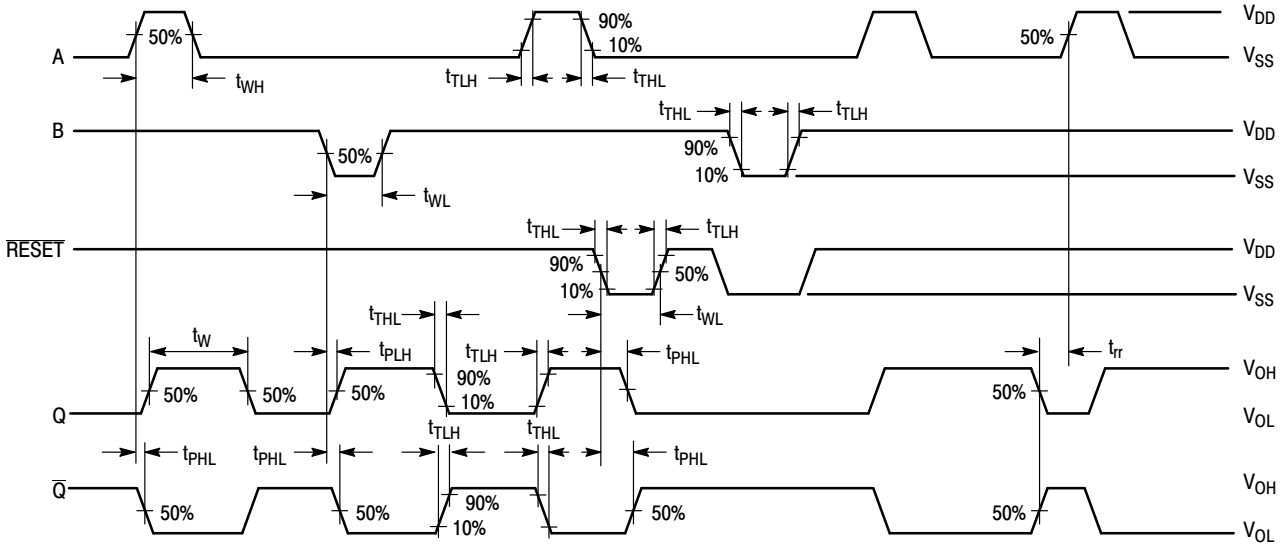


Figure 5. AC Test Waveforms

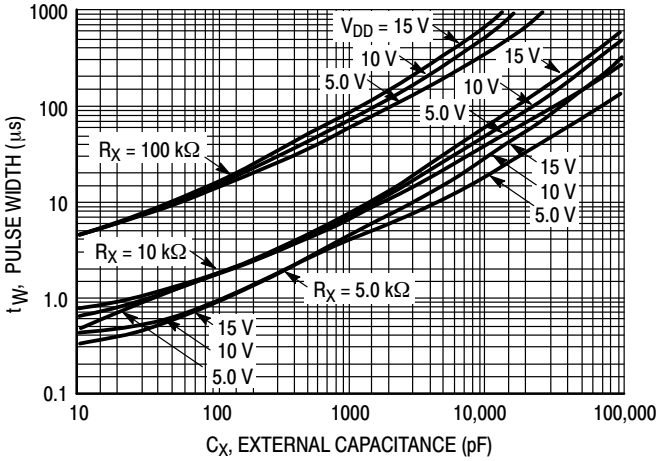


Figure 6. Pulse Width versus C_X

TYPICAL APPLICATIONS

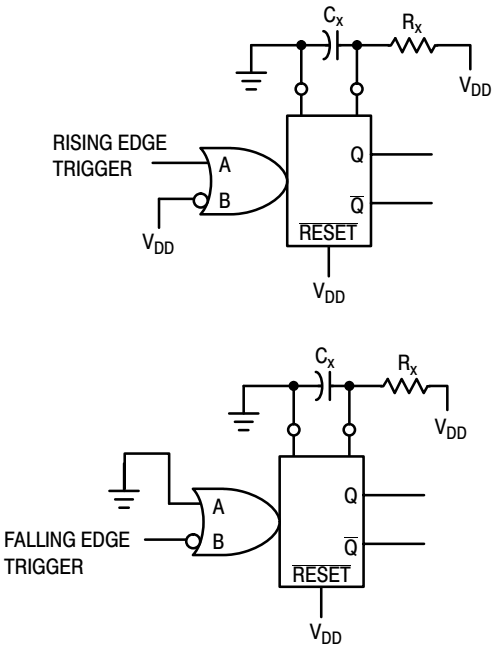


Figure 7. Retriggerable Monostables Circuitry

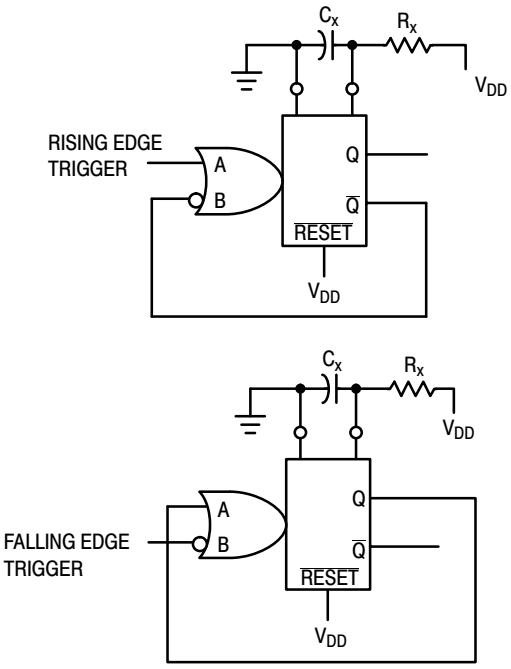


Figure 8. Non−Retriggerable Monostables Circuitry

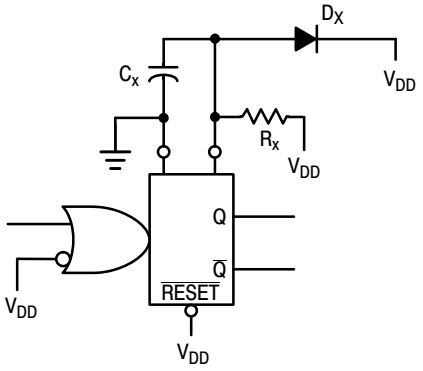


Figure 9. Use of a Diode to Limit Power Down Current Surge

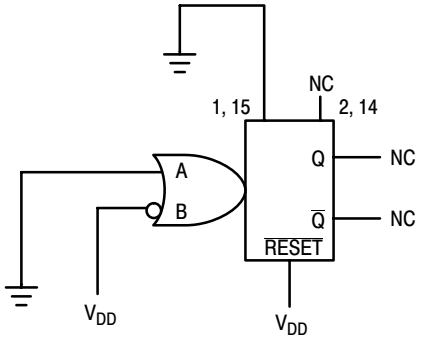
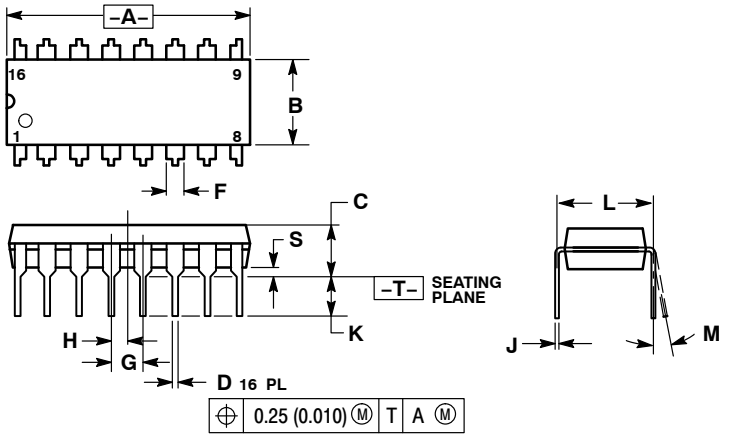


Figure 10. Connection of Unused Sections

PACKAGE DIMENSIONS

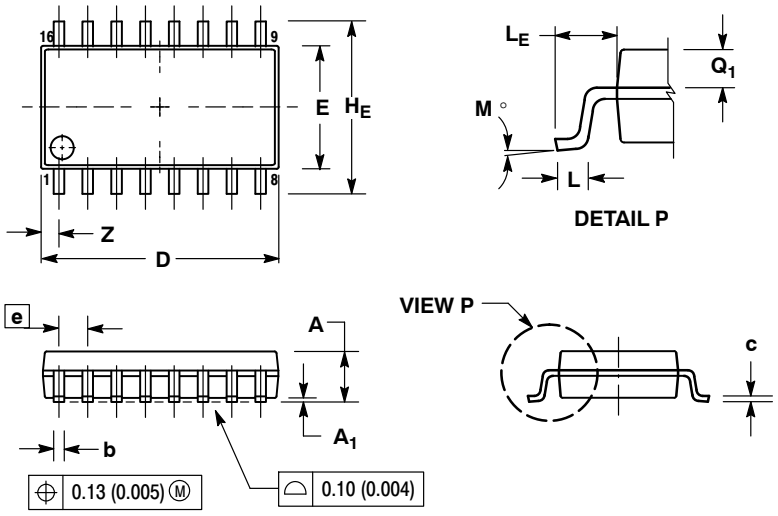
PDIP−16
CASE 648−08
ISSUE T



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
5. ROUNDED CORNERS OPTIONAL.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.740	0.770	18.80	19.55
B	0.250	0.270	6.35	6.85
C	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100 BSC		2.54 BSC	
H	0.050 BSC		1.27 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0 °	10 °	0 °	10 °
S	0.020	0.040	0.51	1.01

SOEIAJ−16
CASE 966−01
ISSUE A

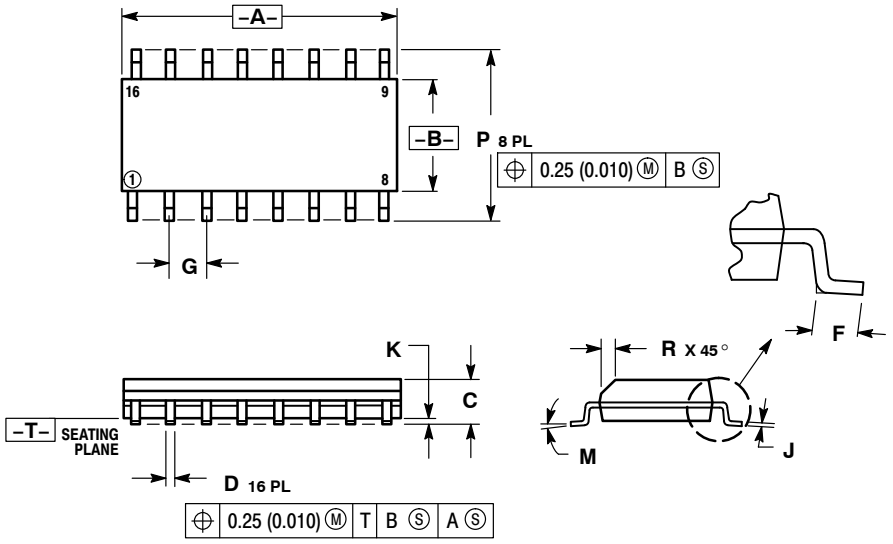


NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	---	2.05	---	0.081
A_1	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
c	0.10	0.20	0.007	0.011
D	9.90	10.50	0.390	0.413
E	5.10	5.45	0.201	0.215
e	1.27 BSC		0.050 BSC	
H_E	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
L_E	1.10	1.50	0.043	0.059
M	0 °	10 °	0 °	10 °
Q_1	0.70	0.90	0.028	0.035
Z	---	0.78	---	0.031

PACKAGE DIMENSIONS

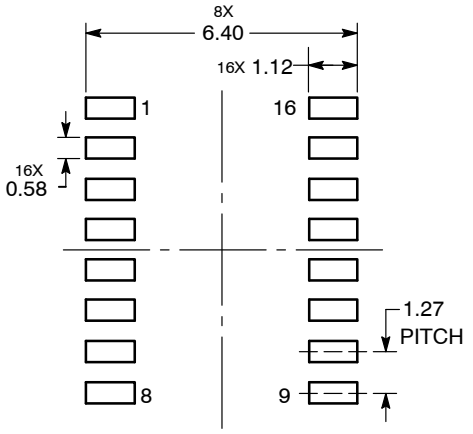
SOIC−16
CASE 751B−05
ISSUE K



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	9.80	10.00	0.386	0.393
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

SOLDERING FOOTPRINT



DIMENSIONS: MILLIMETERS

ECLinPS is a trademark of Semiconductor Components Industries, LLC (SCILLC).

ON Semiconductor and ON are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:
Literature Distribution Center for ON Semiconductor
P.O. Box 5163, Denver, Colorado 80217 USA
Phone: 303−675−2175 or 800−344−3860 Toll Free USA/Canada
Fax: 303−675−2176 or 800−344−3867 Toll Free USA/Canada
Email: orderlit@onsemi.com

N. American Technical Support: 800−282−9855 Toll Free USA/Canada
Europe, Middle East and Africa Technical Support:
Phone: 421 33 790 2910
Japan Customer Focus Center
Phone: 81−3−5773−3850

ON Semiconductor Website: **www.onsemi.com**

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative